

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-28 (Canceled).

Claim 29 (Currently Amended): A semiconductor apparatus comprising:

a semiconductor device;

a plurality of lead wires connected to a plurality of connecting electrodes formed on said semiconductor device;

at least a first pair of dummy lead wires and at least a second pair of dummy lead wires, which ~~[[that]]~~ are not electrically connected to said semiconductor device and do not include an outer lead portion for electrically connecting said semiconductor device to an external circuit of said semiconductor device, tip portions of said at least the first and second pairs ~~[[pair]]~~ of dummy lead wires extending over the semiconductor device;

an insulating film having an opening portion configured to accommodate said semiconductor device and to support said plurality of lead wires connected to the plurality of connecting electrodes of the semiconductor device and said at least the first and second pairs ~~[[pair]]~~ of dummy lead wires, said opening portion having ~~a plurality of four~~ four sides that define a perimeter of said opening portion, two of the four sides are opposite to each other in a first direction and form first opposite sides, and the other two of the four sides are opposite to each other in a second direction and form second opposite sides; and

a resin molding configured to cover a connecting portion between tip portions of the plurality of lead wires and the plurality of connecting electrodes and the tip portions of said at least the first and second pairs ~~[[pair]]~~ of dummy lead wires within the opening portion of said insulating film,

wherein one and the other of said at least the first pair of dummy lead wires are provided on one ~~[[side]]~~ and the other of the first opposite sides ~~an opposite side of said plurality of sides of~~ said insulating film, respectively, one and the other of said at least the second pair of dummy lead wires are provided on one and the other of the second opposite sides of said insulating film, respectively, each of the one and the other of said at least the first pair of dummy lead wires being arranged in corresponding first and second spaces defined by first and second two adjacent lead wires of said plurality of lead wires, respectively, so that a length of each of said first and second spaces is at least twice a minimum pitch between adjacent lead wires of said plurality of lead wires, said first two adjacent lead wires being provided on said one side of the first opposite sides of said insulating film to define said first space on said one side of said insulating film, and said second two adjacent lead wires being provided on said opposite side of the first opposite sides of said insulating film to define said second space on said opposite side of said insulating film.

Claim 30 (Canceled).

Claim 31 (Previously Presented): A semiconductor apparatus according to claim 29, wherein a semiconductor chip in which the semiconductor device is formed has a thickness of approximately 50  $\mu\text{m}$ .

Claims 32-36 (Canceled).

Claim 37 (Currently Amended): A semiconductor apparatus according to claim 29, wherein the tip portions of the at least [[a]] the first or second pair of dummy wires are connected to each other over the semiconductor device.

Claim 38 (New): A semiconductor apparatus according to claim 29, wherein the plurality of lead wires are arranged on the one and the other of the first opposite side of the insulating film.